

WEST Search History for Application 10589912

Creation Date: 2010100714:11

374/170USPT ADJ YES 03-06-2009

((374/120, 121;250/338.1)![CCLS]PGPB, USPT, USOC, EPAB, JPAB ADJ 03-06-2009
((374/120, 121;250/338.1)![CCLS]) and (semiconductor near circuit or integrated circuit or
circuit board or PCB)PGPB, USPT, USOC, EPAB, JPAB ADJ YES 03-06-2009
((374/120, 121;250/338.1)![CCLS] and (semiconductor near circuit or integrated circuit or
circuit board or PCB)) and (thermal near imag\$3 or infrared imag\$3 or infrared camera or
thermal camera or thermograph\$3 or thermal scan\$4)PGPB, USPT, USOC, EPAB,
JPAB ADJ YES 03-06-2009

((374/120, 121;250/338.1)![CCLS] and (semiconductor near circuit or integrated circuit or
circuit board or PCB) and (thermal near imag\$3 or infrared imag\$3 or infrared camera or
thermal camera or thermograph\$3 or thermal scan\$4)) and (heat sink or spreader or cooling
or coolant)PGPB, USPT, USOC, EPAB, JPAB ADJ YES 03-06-2009

((374/120, 121;250/338.1)![CCLS] and (semiconductor near circuit or integrated circuit or
circuit board or PCB) and (thermal near imag\$3 or infrared imag\$3 or infrared camera or
thermal camera or thermograph\$3 or thermal scan\$4)) and (heat sink)PGPB, USPT, USOC,
EPAB, JPAB ADJ YES 03-06-2009

((374/120, 121;250/338.1)![CCLS] and (semiconductor near circuit or integrated circuit or
circuit board or PCB) and (thermal near imag\$3 or infrared imag\$3 or infrared camera or
thermal camera or thermograph\$3 or thermal scan\$4)) and (control\$3 or regulat\$3 or
adjust\$3 or power near remov\$3)PGPB, USPT, USOC, EPAB, JPAB ADJ YES 03-06-2009
((374/120, 121;250/338.1)![CCLS] and (semiconductor near circuit or integrated circuit or
circuit board or PCB) and (thermal near imag\$3 or infrared imag\$3 or infrared camera or
thermal camera or thermograph\$3 or thermal scan\$4)) and (power near control\$3 or power
near regulat\$3 or power near adjust\$3 or power near remov\$3)PGPB, USPT, USOC, EPAB,
JPAB ADJ YES 03-06-2009

(374/170 and (verbitsky) and (integrated circuit)) and (bowden)PGPB, USPT, USOC, EPAB,
JPAB ADJ YES 03-06-2009

((374/120, 121;250/338.1)![CCLS] and (semiconductor near circuit or integrated circuit or
circuit board or PCB) and (thermal near imag\$3 or infrared imag\$3 or infrared camera or
thermal camera or thermograph\$3 or thermal scan\$4) and (control\$3 or regulat\$3 or adjust\$3
or power near remov\$3)) and (overheat\$3)PGPB, USPT, USOC, EPAB,
JPAB ADJ YES 03-06-2009

(374/121, 120, 170, 29, 137, 4, 5, 43, 44, 45, 57, 100, 112;250/338.1;702/130, 131, 132, 133, 134,
135, 136)![CCLS]PGPB, USPT, USOC, EPAB, JPAB ADJ 03-06-2009

((374/121, 120, 170, 29, 137, 4, 5, 43, 44, 45, 57, 100, 112;250/338.1;702/130, 131, 132, 133, 134,
135, 136)![CCLS]) and (integrated circuit or IC or chip or die or PCB or printed near circuit or
circuit near board)PGPB, USPT, USOC, EPAB, JPAB ADJ YES 03-06-2009

((374/121, 120, 170, 29, 137, 4, 5, 43, 44, 45, 57, 100, 112;250/338.1;702/130, 131, 132, 133, 134,
135, 136)![CCLS] and (integrated circuit or IC or chip or die or PCB or printed near circuit or
circuit near board)) and (thermal camera or thermal imag\$3 or thermal scan\$\$ or infrared
camera or infrared imag\$3 or infrared scan\$3 or thermograph\$4 or radiation near detect\$3 or
infrared near sens\$3 or infrared near detect\$3 or IR camera)PGPB, USPT, USOC, EPAB,
JPAB ADJ YES 03-06-2009

(testing or examin\$4 or inspect\$3 or test or NDE or nondestructiv\$4 or DUT or device under
test) same (integrated circuit or IC or chip or die or PCB or printed near circuit or circuit near
board)PGPB, USPT, USOC, EPAB, JPAB ADJ YES 03-06-2009

((testing or examin\$4 or inspect\$3 or test or NDE or nondestructiv\$4 or DUT or device under test) same (integrated circuit or IC or chip or die or PCB or printed near circuit or circuit near board)) and ((374/121, 120, 170, 29, 137, 4, 5, 43, 44, 45, 57, 100, 112;250/338.1;702/130, 131, 132, 133, 134, 135, 136)!CCLS) PGPB, USPT, USOC, EPAB, JPAB ADJ YES 03-06-2009

((testing or examin\$4 or inspect\$3 or test or NDE or nondestructiv\$4 or DUT or device under test) same (integrated circuit or IC or chip or die or PCB or printed near circuit or circuit near board) and (374/121, 120, 170, 29, 137, 4, 5, 43, 44, 45, 57, 100, 112;250/338.1;702/130, 131, 132, 133, 134, 135, 136)!CCLS) and (thermal camera or thermal imag\$3 or thermal scan\$\$ or infrared camera or infrared imag\$3 or infrared scan\$3 or thermograph\$4 or radiation near detect\$3 or infrared near sens\$3 or infrared near detect\$3 or IR camera) PGPB, USPT, USOC, EPAB, JPAB ADJ YES 03-06-2009

((testing or examin\$4 or inspect\$3 or test or NDE or nondestructiv\$4 or DUT or device under test) same (integrated circuit or IC or chip or die or PCB or printed near circuit or circuit near board) and (374/121, 120, 170, 29, 137, 4, 5, 43, 44, 45, 57, 100, 112;250/338.1;702/130, 131, 132, 133, 134, 135, 136)!CCLS) and (thermal camera or thermal imag\$3 or thermal scan\$\$ or infrared camera or infrared imag\$3 or infrared scan\$3 or thermograph\$4 or radiation near detect\$3 or infrared near sens\$3 or infrared near detect\$3 or IR camera) and (power near control\$3 or power near regulat\$3 or power near adjust\$3 or power near remov\$3) PGPB, USPT, USOC, EPAB, JPAB ADJ YES 03-06-2009

Prior Art Searches

Query	DB	Op.	Plur.	Thes.	Date
20050094706	USPT	ADJ	YES		11-16-2009
20050094706	PGPB	ADJ	YES		11-16-2009
10589912	PGPB, USPT	ADJ	YES		11-16-2009
(10589912) and (hollow part)	PGPB, USPT	ADJ	YES		11-16-2009
6162659.pn.	USPT	ADJ	YES		11-16-2009
(10589912) and (overlap)	PGPB	ADJ	YES		11-16-2009
(transparent) near (heat pipe or thermal interface or heat interface or heat near spread\$3 or thermal\$3 near spread\$3 or cool\$3 near plate or heat\$3 near plate or cold near plate or cool\$3 near pipe or thermal\$3 near pipe or coolant or diffus\$3 near pipe or diffus\$3 near rod or diffus\$3 near tube or heat near tube or heat near rod or thermal\$3 near rod or heat sink or heat near interface or cool\$3 near tube)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		11-16-2009
(transparent) near (heat pipe or thermal interface or heat interface or heat near spread\$3 or thermal\$3 near spread\$3 or cool\$3 near plate or heat\$3 near plate or cold near plate or cool\$3 near pipe or thermal\$3 near pipe or coolant or diffus\$3 near pipe or diffus\$3 near	PGPB, USPT, USOC, EPAB, JPAB,	ADJ	YES		11-16-2009

rod or diffus\$3 near tube or heat near tube or heat near rod or thermal\$3 near rod or heat sink or heat near interface or cool\$3 near tube or cool\$3 near duct or cool\$3 near rod) same (IC or chip or semiconductor or integrated circuit or printed near circuit or circuit near board or die)	DWPI, TDBD				
(361/704, 709, 710, 711;257/467/324/760, 763, 765;374/170, 171, 172, 173, 178, 4, 5, 29, 120, 121, 137, 43, 44;702/130, 131, 132, 133, 134, 135, 136;250/338.1)! [CCLS]	PGPB, USPT, USOC, EPAB, JPAB	ADJ	YES		11-16-2009
(heat pipe or thermal interface or heat interface or heat near spread\$3 or thermal\$3 near spread\$3 or cool\$3 near plate or heat\$3 near plate or cold near plate or cool\$3 near pipe or thermal\$3 near pipe or coolant or diffus\$3 near pipe or diffus\$3 near rod or diffus\$3 near tube or heat near tube or heat near rod or heat sink or heat near interface or cool\$3 near tube or cool\$3 near duct or cool\$3 near rod) same (IC or chip or semiconductor or integrated circuit or printed near circuit or circuit near board or die)	PGPB, USPT, USOC, EPAB, JPAB	ADJ	YES		11-16-2009
(361/704, 709, 710, 711;257/467;324/760, 763, 765;374/170, 171, 172, 173, 178, 4, 5, 29, 120, 121, 137, 43, 44;702/130, 131, 132, 133, 134, 135, 136;250/338.1)! [CCLS]	PGPB, USPT, USOC, EPAB, JPAB	ADJ	YES		11-16-2009
((361/704, 709, 710, 711;257/467;324/760, 763, 765;374/170, 171, 172, 173, 178, 4, 5, 29, 120, 121, 137, 43, 44;702/130, 131, 132, 133, 134, 135, 136;250/338.1)! [CCLS]) and ((heat pipe or thermal interface or heat interface or heat near spread\$3 or thermal\$3 near spread\$3 or cool\$3 near plate or heat\$3 near plate or cold near plate or cool\$3 near pipe or thermal\$3 near pipe or coolant or diffus\$3 near pipe or diffus\$3 near rod or diffus\$3 near tube or heat near tube or heat near rod or thermal\$3 near rod or heat sink or heat near interface or cool\$3 near tube or cool\$3 near duct or cool\$3 near rod) same (IC or chip or semiconductor or integrated circuit or printed near circuit or circuit near board or die))	PGPB, USPT, USOC, EPAB, JPAB	ADJ	YES		11-16-2009
((361/704, 709, 710, 711;257/467;324/760, 763, 765;374/170, 171, 172, 173, 178, 4, 5, 29, 120, 121, 137, 43, 44;702/130, 131, 132, 133, 134, 135, 136;250/338.1)! [CCLS]) and (heat pipe or thermal interface or heat interface or heat near spread\$3 or thermal\$3 near spread\$3 or cool\$3 near plate or heat\$3 near plate or cold near plate or cool\$3 near pipe or	PGPB, USPT, USOC, EPAB, JPAB	ADJ	YES		11-16-2009

thermal\$3 near pipe or coolant or diffus\$3 near pipe or diffus\$3 near rod or diffus\$3 near tube or heat near tube or heat near rod or thermal\$3 near rod or heat sink or heat near interface or cool\$3 near tube or cool\$3 near duct or cool\$3 near rod) same (IC or chip or semiconductor or integrated circuit or printed near circuit or circuit near board or die)				
((361/704, 709, 710, 711;257/467;324/760, 763, 765;374/170, 171, 172, 173, 178, 4, 5, 29, 120, 121, 137, 43, 44;702/130, 131, 132, 133, 134, 135, 136;250/338.1)!)[CCLS] and (heat pipe or thermal interface or heat interface or heat near spread\$3 or thermal\$3 near spread\$3 or cool\$3 near plate or heat\$3 near plate or cold near plate or cool\$3 near pipe or thermal\$3 near pipe or coolant or diffus\$3 near pipe or diffus\$3 near rod or diffus\$3 near tube or heat near tube or heat near rod or thermal\$3 near rod or heat sink or heat near interface or cool\$3 near tube or cool\$3 near duct or cool\$3 near rod) same (IC or chip or semiconductor or integrated circuit or printed near circuit or circuit near board or die) and ((transparent) near (heat pipe or thermal interface or heat interface or heat near spread\$3 or thermal\$3 near spread\$3 or cool\$3 near plate or heat\$3 near plate or cold near plate or cool\$3 near pipe or thermal\$3 near pipe or coolant or diffus\$3 near pipe or diffus\$3 near rod or diffus\$3 near tube or heat near tube or heat near rod or thermal\$3 near rod or heat sink or heat near interface or cool\$3 near tube or cool\$3 near duct or cool\$3 near rod) same (IC or chip or semiconductor or integrated circuit or printed near circuit or circuit near board or die))	PGPB, USPT, USOC, EPAB, JPAT	ADJ	YES	11-16-2009
(702/130, 131, 132, 133, 134, 135, 136, 99;374/170, 171, 172, 100, 32, 39, 134, 175, 4, 5, 120, 121, 137, 29, 43, 44, 1;361/704, 710, 711, 709;257/467;324/760, 763, 765)!)[CCLS]	PGPB, USPT, USOC, EPAB, JPAT	ADJ	YES	10-07-2010
transparent near cool\$3	PGPB, USPT, USOC, EPAB, JPAT	ADJ	YES	10-07-2010
(transparent near cool\$3) and ((702/130, 131, 132, 133, 134, 135, 136, 99;374/170, 171, 172, 100, 32, 39, 134, 175, 4, 5, 120, 121, 137, 29, 43, 44, 1;361/704, 710, 711, 709;257/467;324/760, 763, 765)!)[CCLS])	PGPB, USPT, USOC, EPAB, JPAT	ADJ	YES	10-07-2010